

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Kenji Shirako</td><td>09/16/2011</td></tr><tr><td>Takatomo Yamaguchi</td><td>09/16/2011</td></tr><tr><td>Shuhei Saido</td><td>09/16/2011</td></tr><tr><td>Akihiro Sato</td><td>09/16/2011</td></tr></tbody></table>	Name	Execution Date	Kenji Shirako	09/16/2011	Takatomo Yamaguchi	09/16/2011	Shuhei Saido	09/16/2011	Akihiro Sato	09/16/2011			
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<table border="1"><tr><td>Name:</td><td>HITACHI KOKUSAI ELECTRIC INC.</td></tr><tr><td>Street Address:</td><td>14-1, Sotokanda 4-chome</td></tr><tr><td>Internal Address:</td><td>Chiyoda-ku</td></tr><tr><td>City:</td><td>Toyko</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>1018980</td></tr></table>	Name:	HITACHI KOKUSAI ELECTRIC INC.	Street Address:	14-1, Sotokanda 4-chome	Internal Address:	Chiyoda-ku	City:	Toyko	State/Country:	JAPAN	Postal Code:	1018980	
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PROPERTY NUMBERS Total: 1													
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Application Number:	13229543												
CORRESPONDENCE DATA													
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ATTORNEY DOCKET NUMBER:	HITACHI12-20910257US01												
NAME OF SUBMITTER:	Daniel N. Calder												
Total Attachments: 2 source=20110922_Executed_Assignment#page1.tif source=20110922_Executed_Assignment#page2.tif													

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PATENT
REEL: 026948 FRAME: 0374

ASSIGNMENT

Kenji Shirako, Takatomo Yamaguchi, Shuhei Saido, Akihiro Sato, residing at Toyama, Japan, citizens of Japan (hereafter the undersigned); are the inventor of Substrate Processing Apparatus and Method of Manufacturing Semiconductor Device for which the undersigned executed an application for United States Letters Patent, U.S. Patent Application No. 13/229,543, filed September 9, 2011.

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Hitachi Kokusai Electric Inc., [a / an] company, having a principal place of business at

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan
(hereafter referred to as the assignee), is desirous of acquiring the entire right, title, and interest in said invention, all applications for, and all letters patent issued on said invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign, and transfer to the assignee and assignee's successors, assigns, and legal representatives the entire right, title, and interest in said invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

EXECUTED under seal on this 16th day of September, 2011

at Tokyo, Japan.
(Place)

Witness:

Kenji Shirako (L.S.)
Kenji Shirako

Takatomo Yamaguchi (L.S.)
Takatomo Yamaguchi

Shuhei Saido (L.S.)
Shuhei Saido

Akihiro Sato (L.S.)
Akihiro Sato

(Although not mandatory, if possible,
please subscribe appropriate notarization and obtain APOSTILLE)